

# 562/564 Series

## Circuit Board Mount Blocks for TE5/TR5 Type Fuses



562 Series Holder

564 Series Holder

### Product Characteristics

	562 Series	564 Series
<b>Compatible Fuses</b>	TR5/TE5	
<b>Materials</b>	Block: Black Thermoplastic, UL94 V-0 PET Terminals: Copper alloy; solderable tinned	
<b>Electrical Data (23°C)</b>	Rated Voltage: 250V Max. Current/Power: 6.3A/1.6W	
<b>Mounting</b>	PC Board, 5.08mm pin spacing	PC Board, 5.08mm pad spacing
<b>Minimum Cross Section</b>	Conducting path - 0.1mm <sup>2</sup>	Conducting path - 0.1mm <sup>2</sup>
<b>Unit Weight</b>	0.12g	0.44g
<b>Ambient Temperature</b>	- 40°C to + 85°C	

### Ordering Information

Ordering Number	Circuit Board Mounting	Packaging
56200001009	Thru-Hole	1000 (Bulk pack)
56400001009	Surface Mount	1500 (Tape /Reel)

### Agency Approvals

Agency	Agency File Number	
	562 Series	564 Series
	E14721	E14721

### Additional Information



Resources  
562 Series



Accessories  
562 Series



Samples  
562 Series



Resources  
564 Series



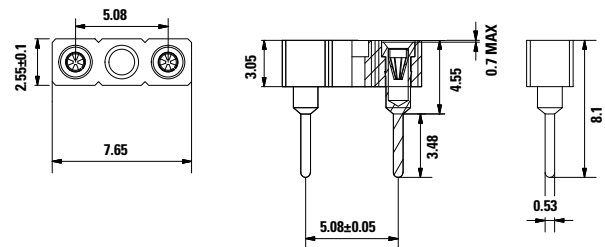
Accessories  
564 Series



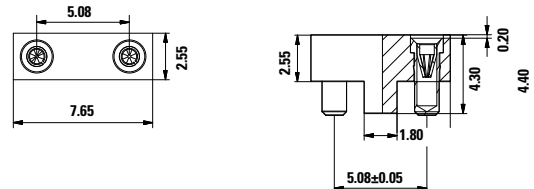
Samples  
564 Series

### Dimensions units in mm

#### 562 Series Holder



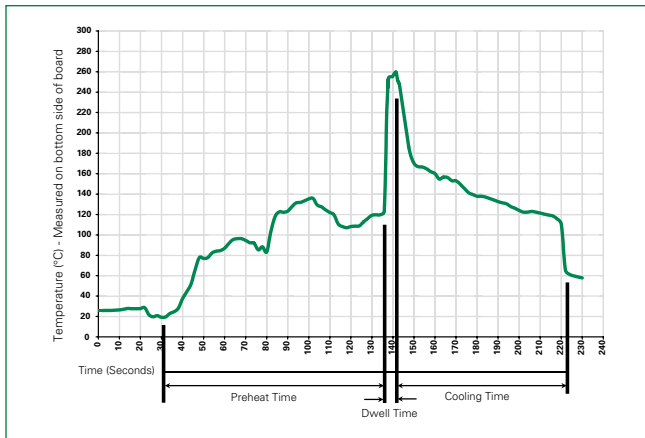
#### 564 Series Holder



# 562/564 Series

## Circuit Board Mount Blocks for TE5/TR5 Type Fuses

### Soldering Parameters - Wave Soldering



#### Recommended Process Parameters:

Wave Parameter	Lead-Free Recommendation
Preheat: (Depends on Flux Activation Temperature)	(Typical Industry Recommendation)
Temperature Minimum:	100°C
Temperature Maximum:	150°C
Preheat Time:	60-180 seconds
Solder Pot Temperature:	260°C Maximum
Solder Dwell Time:	2-5 seconds

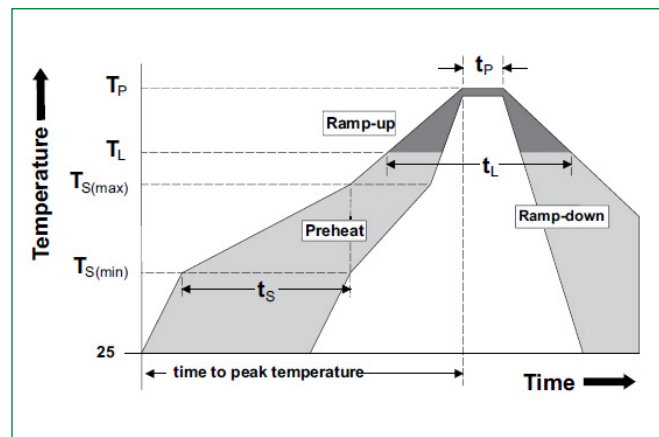
#### Recommended Hand-Solder Parameters:

Solder Iron Temperature: 350°C +/- 5°C  
Heating time: 5 seconds max

**Note:** These devices are not recommended for IR and Convection Reflow process

### Soldering Parameters - Reflow Soldering

<b>Reflow Condition</b>	Pb - Free assembly	
<b>Number of allowed reflow cycles</b>	3	
<b>Pre Heat</b>	-Temperature Min ( $T_{s(min)}$ )	150°C
	-Temperature Max ( $T_{s(max)}$ )	200°C
	-Time (Min to Max) ( $t_p$ )	60 - 120 Secs.
<b>Average ramp up rate (Liquidus Temp (<math>T_L</math>) to peak)</b>	5°C/second max.	
<b><math>T_{s(max)}</math> to <math>T_L</math> - Ramp-up Rate</b>	5°C/second max.	
<b>Reflow</b>	- Temperature ( $T_L$ ) (Liquidus)	217°C
	-Temperature ( $t_l$ )	60 - 150 seconds
<b>Peak Temperature (<math>T_p</math>)</b>	240 <sup>+/-5</sup> °C	
<b>Time within 50C of actual peak Temperature (<math>t_p</math>)</b>	30 secs. max.	
<b>Ramp-down Rate</b>	5°C/second max.	
<b>Time 25°C to peak Temperature (<math>T_p</math>)</b>	8 minutes max.	
<b>Do not exceed</b>	245°C	



**Disclaimer Notice** - Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and may not be used in, all applications. Read complete Disclaimer Notice at: [www.littelfuse.com/disclaimer-electronics](http://www.littelfuse.com/disclaimer-electronics).